

Metallization System **MINIMET**



Key Figures

- Technology: DC-Magnetron Sputtering or HIPIMS
MF-Plasma Activation & Polymerization
- Cycle time: min. 40 sec
- Carrier size: 300 mm x 200 mm x 120 mm (L x W x H)
- Footprint: 6,000 mm x 4,250 mm (incl. handling and service area)

Applications

Metallization of:

- Reflectors in automotive- & lighting industry
- Decorative components in automotive industry
- Consumer products & household appliances

Features

- Coating with all metals that can be sputtered and SiO_x top coat
- Short cycle time down to 40 sec due to multi chamber system
- Horizontal material flow
- Ready for automatic substrate loading and –unloading
- Compact design for fast installation
- Data logging for process analysis and quality control

Customer Benefits

- Ready for integration into lean production flow with robotic loading/unloading
- Small footprint, matches injection moulding system
- Simple substrate mounting, substrate rotation optional
- Pick and place substrate holding suitable for robotic handling
- Plug and play operation
- Industry 4.0 – ready

Standard Coating Materials

- Aluminium
- Chromium
- Titanium
- Stainless steel